

**Processing Guide  
Secondary Insulation**

**PG-113 –  
Dip Solvent Borne Resin**

## Processing Guide PG-113 – Dip Solvent Borne Resin Process

Process Step	Optimum	Minimum	Comments
<i>Preheat</i>	1 hour at 135 - 150°C(275 - 300°F) Once unit reaches temperature	None	Relax magnet wire, drives out moisture, thermosets tapes, assists in penetration
<i>Part Temperature when resin is introduced</i>	50 – 55°C (120 - 130°F)	25 – 50°C (77°F – 120°F)	Temperature has a direct bearing on varnish penetration. If too low varnish will not penetrate fully. If too high varnish can be damaged
<i>Submerge Units</i>	4 inches per minute	Slow as possible	Hold to 10 – 15 minutes or until bubbles cease
<i>Raise units</i>	4 inches per minute	Slow as possible	Slow removal allows good flow
<i>Drain Time</i>	10-15 minutes	None	Longer drain will re-capture more resin.
<i>Bake Schedule</i>	As recommended by product data sheet.	As recommended by product data sheet.	Full cure is required to develop all performance properties.

Please contact ELANTAS PDG, Inc. Technical Service if you have any questions.

Phone number 1.314.621.5700 Extension 717 or 1.800.325.7492 Extension 717

The above properties are typical values and are not intended for specification use.

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